



Product Change Notification / JAON-09TGWM044

Date:

17-Jan-2023

Product Category:

Analog Temperature Sensors, Analog to Digital Converters, Digital Potentiometers, Digital to Analog Converters

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5278 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP3421xxx, MCP3425Axx, MCP401xx, MCP402xx, MCP4706Axx, MCP4716Axx, MCP4725Axx, MCP4726Axx, MCP47DA1T, and MCP9510xx device families available in 6L SOT-23 package assembled at MMT assembly site.

Affected CPNs:

[JAON-09TGWM044_Affected_CPN_01172023.pdf](#)

[JAON-09TGWM044_Affected_CPN_01172023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP3421xxx, MCP3425Axx, MCP401xx, MCP402xx, MCP4706Axx, MCP4716Axx, MCP4725Axx, MCP4726Axx, MCP47DA1T, and MCP9510xx device families available in 6L SOT-23 package assembled at MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	84-3J/8006NS	84-3J/8006NS
Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	CDA194

Impacts to Data Sheet:None

Change Impact:None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: February 16, 2023 (date code: 2307)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2022					->	January 2023					February 2023				
	3 6	3 7	3 8	3 9	4 0		1	2	3	4	5	6	7	8	9	10
Initial PCN Issue Date			X													
Qual Report Availability								X								
Final PCN Issue Date									X							
Estimated Implementation												X				

Date | | | | | | | | | | | | | | | |

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:September 13, 2022: Issued initial notification.

January 17, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on February 16, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_JAON-09TGWM044_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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